



SANYO Semiconductors

DATA SHEET

An ON Semiconductor Company

LV56831P — Monolithic Linear IC For Car Audio Systems Multi Voltage Regulator IC

Overview

The LV56831P has 4 system regulator, V_{DD} 5V(3.3V), AUDIO(8.5V), AMP remote(12V) and REG(3.3V/5V select). About protection circuits, it has Over-current-protection, Over-voltage-protection and Thermal-shut-down. AMP remote and REG supply is independent terminal from V_{CC} .

Features

- 4 system regulator
 - V_{DD} (LCD micon) : V_{OUT} 5.0V(3.3V), I_O max 300mA, reverse current prevention.
 - Audio : V_{OUT} 8.5V, I_O max 400mA
 - AMP remote : V_{OUT} 12V, I_O max 500mA
 - REG3.3/5V : V_{OUT} 3.3V(5V), I_O max 500mA
- Over-current-protection
- Thermal-shut-down Typ 175°C
- Over-voltage-protection: Typ 21V(except V_{DD})
- Applied Pch-LDMOS for output stages.

(Warning)The protector functions only improve the IC's tolerance and they do not guarantee the safety of the IC if used under the conditions out of safety range or ratings. Use of the IC such as use under overcurrent protection range or thermal shut down state may degrade the IC's reliability and eventually damage the IC.

Specifications

Absolute Maximum Ratings at $T_a = 25^\circ\text{C}$

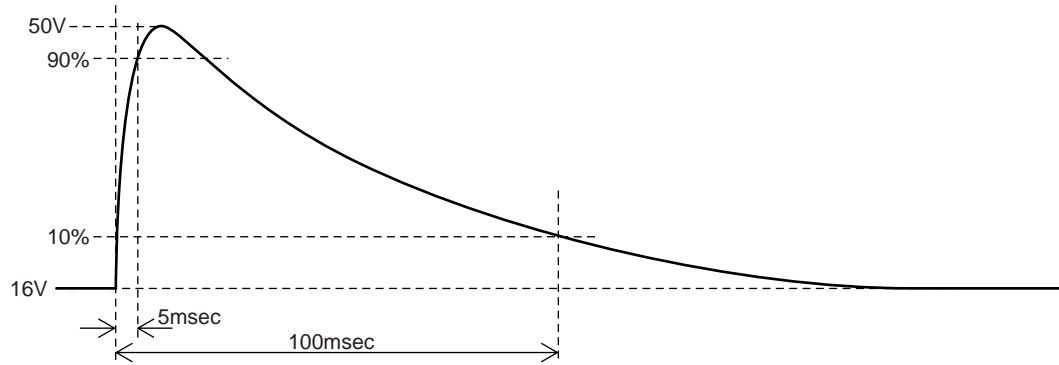
Parameter	Conditions	Conditions	Ratings	Unit
Supply voltage	V_{CC} max		36	V
Allowable Power dissipation	P_d max (* $T_a \leq 25^\circ\text{C}$)	IC unit	1.3	W
		With Al heatsink(50×50×1.5mm ³)	5.3	W
		Infinite heat radiation	26	W
Peak supply voltage	V_{CC} peak	See below pulse wave.	50	V
Operating ambient temperature	T_{opr}		-40 to +85	°C
Storage temperature	T_{stg}		-55 to +150	°C
Junction temperature	T_j max		150	°C

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Peak voltage testing pulse wave



Recommended Operating condition at $T_a = 25^\circ\text{C}$

Parameter	Conditions	Ratings	Unit
Power supply voltage rating 1	V_{DD} output(5V/3.3V)	7 to 16	V
Power supply voltage rating 2	REG output(5V/3.3V): $V_{CC}=V_{CC1}$	7 to 16	V
Power supply voltage rating 3	AUDIO output	11 to 16	V
Power supply voltage rating 4	AMP remote output: $V_{CC}=V_{CC1}$	13 to 16	V

Electrical Characteristics at $T_a = 25^\circ\text{C}$, $V_{CC} = V_{CC1} = 14.4\text{V}$ (*1)

Parameter	Symbol	Conditions	Ratings			Unit
			min	typ	max	
Quiescent current	I_{CC}	V_{DD} no load, ALL EN terminal = [L]		50	100	μA
AUDIO_EN Input						
Low input voltage	V_{IL1}		0		0.5	V
High input voltage	V_{IH1}		2.0		5.5	V
Input impedance	R_{IH1}		280	400	520	$\text{k}\Omega$
AMP_EN Input						
Low input voltage	V_{IL2}		0		0.5	V
High input voltage	V_{IH2}		2.0		5.5	V
Input impedance	R_{IH2}		280	400	520	$\text{k}\Omega$
REG_EN input						
Low input voltage	V_{IL3}		0		0.5	V
High input voltage	V_{IH3}		2.0		5.5	V
Input impedance	R_{IH3}		280	400	520	$\text{k}\Omega$
V_{DD} (5V/3.3V)output(reverse current prevention diode implemented)						
V_{DD} output voltage 1	V_{O11}	$I_{O11} = 200\text{mA}$, IKV_{DD} is connected to 5PIN.	4.75	5.0	5.25	V
V_{DD} output current 1	I_{O11}	$V_{O11} \geq 4.7\text{V}$	300			mA
V_{DD} output voltage 2	V_{O12}	$I_{O12} = 200\text{mA}$, $IKV_{DD} = \text{GND}$	3.13	3.3	3.47	V
V_{DD} output current 2	I_{O12}	$V_{O12} \geq 3.1\text{V}$	300			mA
Line regulation	ΔV_{OLN1}	$7\text{V} < V_{CC} < 16\text{V}$, $I_{O1} = 200\text{mA}$		50	100	mV
Load regulation	ΔV_{OLD1}	$1\text{mA} < I_{O11}, I_{O12} < 200\text{mA}$		80	150	mV
Dropout voltage 1	V_{DROP1}	$I_{O1} = 200\text{mA}$ (implemented diode)		1.5	2.5	V
V_{CC} ripple rejection	R_{REJ1}	$f=120\text{Hz}$, $I_{O1}=200\text{mA}$	40(*2)	50(*2)		dB
V_{DD} reverse current	I_{REV}	$V_{O11}=5.0\text{V}$, $V_{CC}=0\text{V}$		10	100	μA
AMP remote output ; AMP_EN = High						
USB output voltage 1	V_{O2}	$I_{O2} = 400\text{mA}$	11.4	12	12.6	V
USB output current 1	I_{O2}	$V_{O2} \geq 11.3\text{V}$	500			mA
Line regulation	ΔV_{OLN2}	$13\text{V} < V_{CC1} < 16\text{V}$, $I_{O2} = 400\text{mA}$		50	100	mV
Load regulation	ΔV_{OLD2}	$10\text{mA} < I_{O2} < 400\text{mA}$		80	160	mV
Dropout voltage 1	V_{DROP2}	$I_{O2} = 400\text{mA}$		0.4	0.8	V
V_{CC1} ripple rejection	R_{REJ2}	$f=120\text{Hz}$, $I_{O2}=400\text{mA}$	40(*2)	50(*2)		dB

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Parameter	Symbol	Conditions	Ratings			Unit
			min	typ	max	
AUDIO output ; AUDIO_EN = High						
AUDIO output voltage	V_{O3}	$I_{O3} = 300\text{mA}$	8.1	8.5	8.9	V
AUDIO output current	I_{O3}	$V_{O3} \geq 8\text{V}$	400			mA
Line regulation	ΔV_{OLN3}	$10\text{V} < V_{CC} < 16\text{V}$, $I_{O3} = 300\text{mA}$		30	100	mV
Load regulation	ΔV_{OLD3}	$1\text{mA} < I_{O3} < 300\text{mA}$		70	140	mV
Dropout voltage	V_{DROP3}	$I_{O3} = 300\text{mA}$		0.6	1.05	V
V_{CC} ripple rejection	R_{REJ3}	$f = 120\text{Hz}$, $I_{O3} = 300\text{mA}$	40(*2)	50(*2)		dB
REG (3.3V/5V) Output ; REG_EN = High						
REG output voltage 1	V_{O41}	$I_{O41} = 400\text{mA}$, IKREG is connected to 10PIN.	4.75	5	5.25	V
REG output current 1	I_{O41}	$V_{O41} \geq 4.7\text{V}$	500			mA
REG output voltage 2	V_{O42}	$I_{O42} = 400\text{mA}$, IKREG=GND	3.13	3.3	3.47	V
REG output current 2	I_{O42}	$V_{O42} \geq 3.1\text{V}$	500			mA
Line regulation	ΔV_{OLN4}	$7\text{V} < V_{CC1} < 16\text{V}$, $I_{O4} = 400\text{mA}$		30	100	mV
Load regulation	ΔV_{OLD4}	$1\text{mA} < I_{O4} < 400\text{mA}$		80	150	mV
Dropout voltage	V_{DROP4}	$I_{O4} = 400\text{mA}$		1.0	1.5	V
V_{CC1} ripple rejection	R_{REJ4}	$f = 120\text{Hz}$, $I_{O4} = 400\text{mA}$	40(*2)	50(*2)		dB

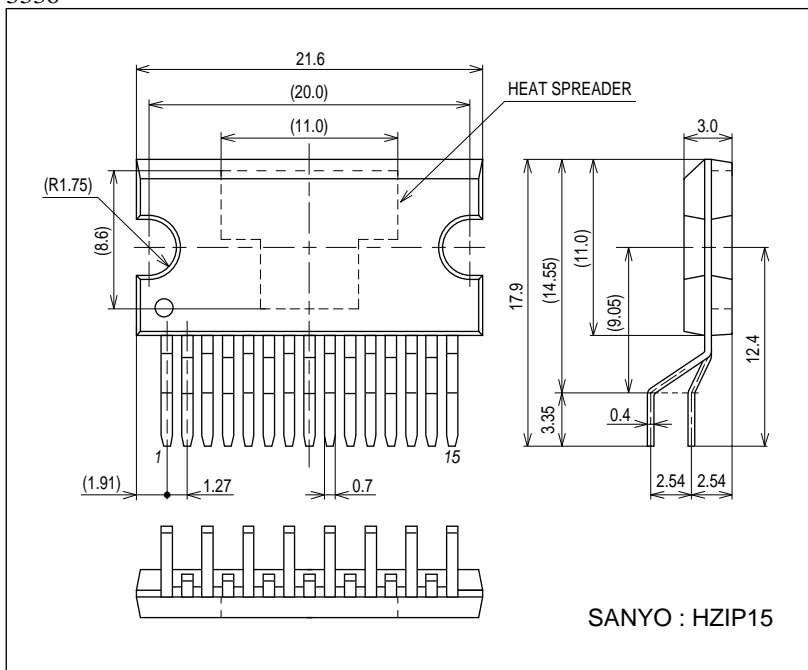
*1: The entire specification has been defined based on the tests performed under the conditions where T_j and $T_a (=25^\circ\text{C})$ are almost equal. There tests were performed with pulse load to minimize the increase of junction temperature(T_j).

*2 : design certification

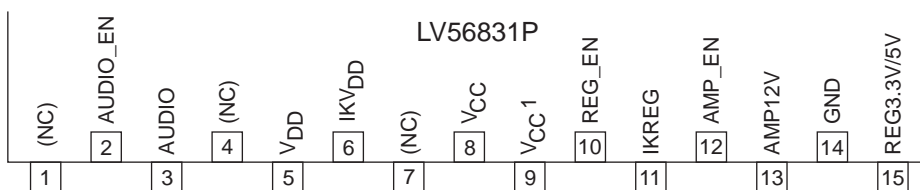
Package Dimensions

unit : mm (typ)

3336

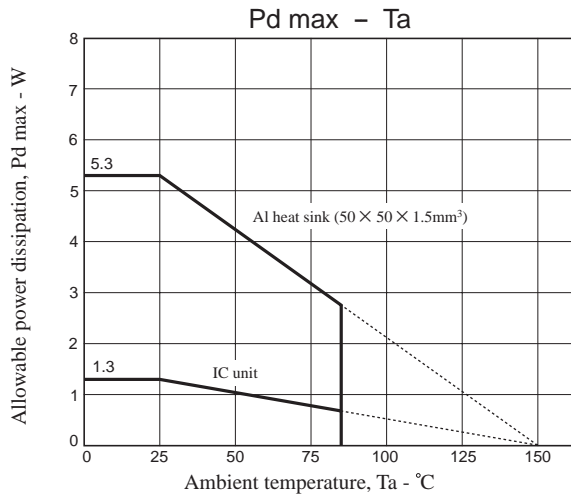


Pin assignment



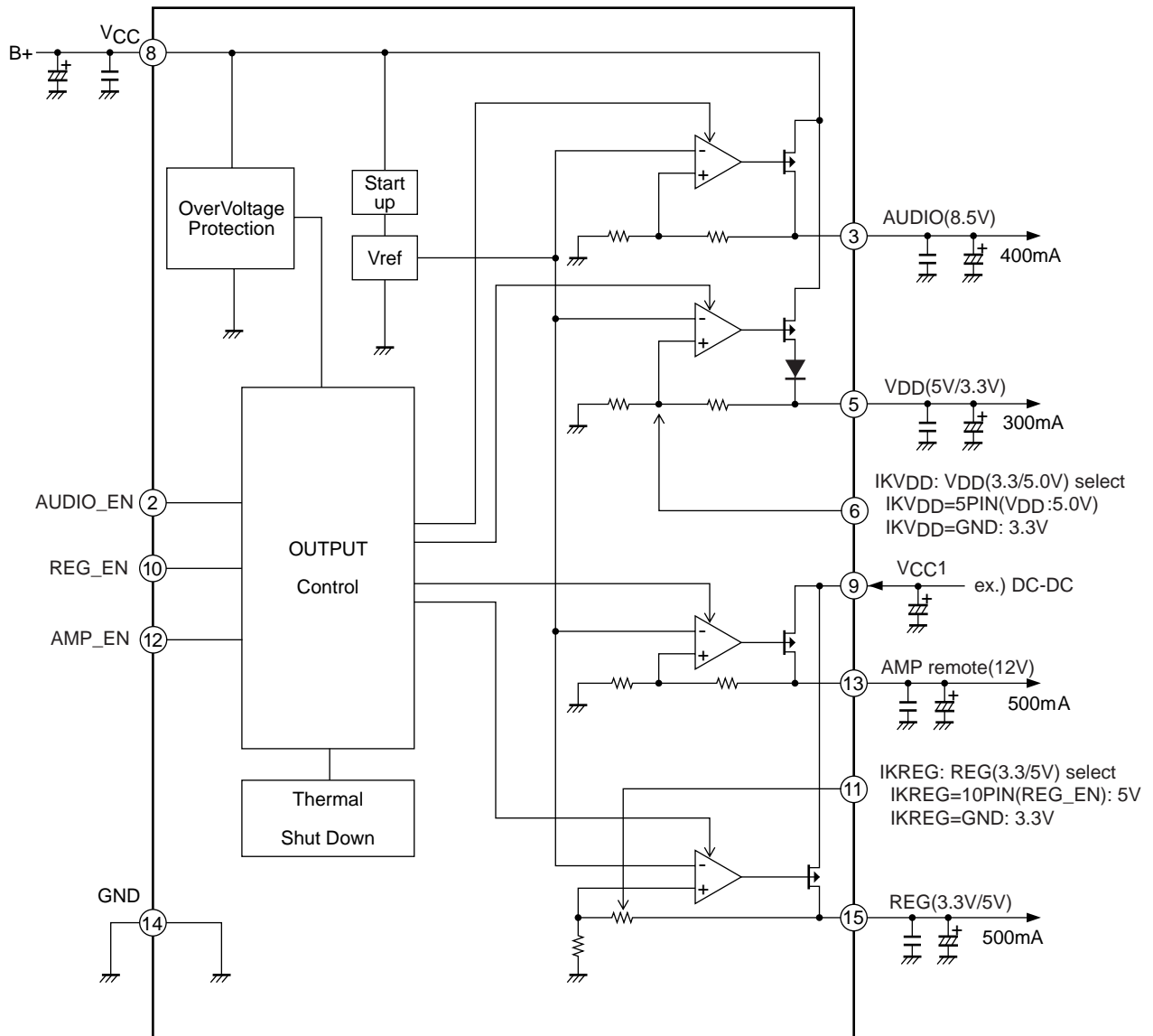
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Allowable power dissipation derating curve



- (a) IC unit(HZIP15)
 - (b) With Al heatsink(50×50×1.5mm³)
- Al heatsink mounting conditions
Tightening torque: 39N-cm, using silicone grease

Block Diagram



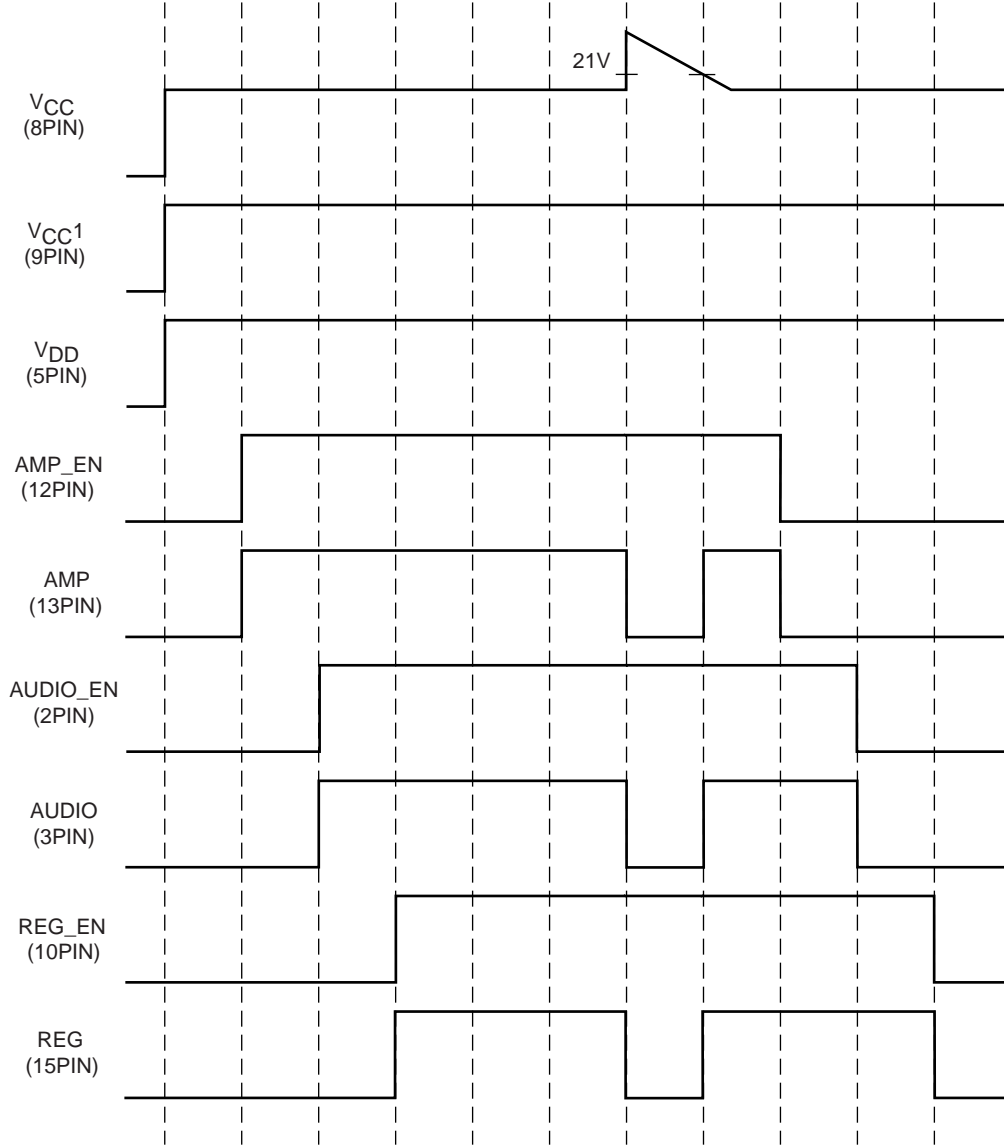
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Pin No.	Pin name	Description	Equivalent Circuit
10	REG_EN	REG output CTRL	
11	IKREG	REG output voltage select OPEN : REG = 3.3V GND : REG = 5.0V	
12	AMP_EN	AMP output CTRL	
13	AMP	AMP output when AMP_EN = High, ON 12V, 0.5A	
14	GND	GND	
15	REG	REG output when REG_EN = High, ON 5.0V, 3.3V/0.5A	

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Timing Chart



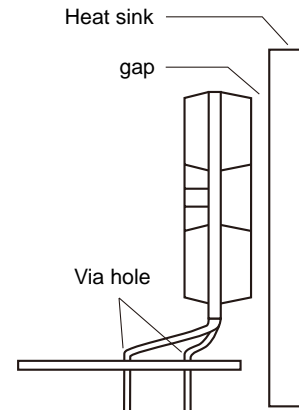
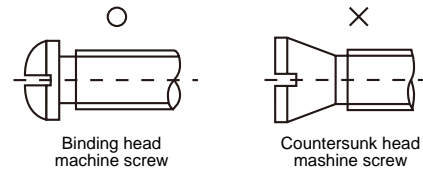
HZIP15 Heat sink attachment

Heat sinks are used to lower the semiconductor device junction temperature by leading the heat generated by the device to the outer environment and dissipating that heat.

- a. Unless otherwise specified, for power ICs with tabs and power ICs with attached heat sinks, solder must not be applied to the heat sink or tabs.

b. Heat sink attachment

- Use flat-head screws to attach heat sinks.
- Use also washer to protect the package.
- Use tightening torques in the ranges 39-59Ncm(4-6kgcm) .
- If tapping screws are used, do not use screws with a diameter larger than the holes in the semiconductor device itself.
- Do not make gap, dust, or other contaminants to get between the semiconductor device and the tab or heat sink.
- Take care a position of via hole .
- Do not allow dirt, dust, or other contaminants to get between the semiconductor device and the tab or heat sink.
- Verify that there are no press burrs or screw-hole burrs on the heat sink.
- Warping in heat sinks and printed circuit boards must be no more than 0.05 mm between screw holes, for either concave or convex warping.
- Twisting must be limited to under 0.05 mm.
- Heat sink and semiconductor device are mounted in parallel.
Take care of electric or compressed air drivers
- The speed of these torque wrenches should never exceed 700 rpm, and should typically be about 400 rpm.



c. Silicone grease

- Spread the silicone grease evenly when mounting heat sinks.
- Sanyo recommends YG-6260 (Momentive Performance Materials Japan LLC)

d. Mount

- First mount the heat sink on the semiconductor device, and then mount that assembly on the printed circuit board.
- When attaching a heat sink after mounting a semiconductor device into the printed circuit board, when tightening up a heat sink with the screw, the mechanical stress which is impossible to the semiconductor device and the pin doesn't hang.

e. When mounting the semiconductor device to the heat sink using jigs, etc.,

- Take care not to allow the device to ride onto the jig or positioning dowel.
- Design the jig so that no unreasonable mechanical stress is not applied to the semiconductor device.

f. Heat sink screw holes

- Be sure that chamfering and shear drop of heat sinks must not be larger than the diameter of screw head used.
- When using nuts, do not make the heat sink hole diameters larger than the diameter of the head of the screws used. A hole diameter about 15% larger than the diameter of the screw is desirable.
- When tap screws are used, be sure that the diameter of the holes in the heat sink are not too small. A diameter about 15% smaller than the diameter of the screw is desirable.

- g. There is a method to mount the semiconductor device to the heat sink by using a spring band. But this method is not recommended because of possible displacement due to fluctuation of the spring force with time or vibration.

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